## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Hui et al.

Serial No.: 09/916,197
Filed: July 26, 2001
For: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A
SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Examiner: Unknown
Group Art Unit: 2841
Attorney Docket No.: 4712US (99-1054)


## LETTER TO THE CHIEF DRAFTSMAN

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231
Sir:
Applicants submit herewith revised FIGS. 1, 3, 4, 4A, 5, 6 and 8C which correct errors in the drawings. Specifically, FIG. 1 has been revised to change lead line location; FIG. 3 has been revised to change reference numeral 24 to 34 and to change reference numeral 34 to 24 to correct reference numerals; FIG. 4 has been revised to add reference numeral 20 with appropriate lead line; FIG. 4A has been revised to add appropriate lead lines for reference 40; FIG. 5 has been revised to add reference numerals 11,31, 32 and 42 with appropriate lead lines; FIG. 6 has been
revised to add reference numerals $12,26,31$ and 32 with appropriate lead lines; and FIG. 8C has been revised to change reference numeral 2 to 5 to eliminate redundancy with previously used reference numerals and to add reference numerals 10 with appropriate lead lines. Attached is a copy of the drawings with the proposed changes marked in red.

No new matter has been added. Approval of the proposed revisions is respectfully requested.

Respectfully submitted,


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BGP/dlm
Enclosures: Drawings with changes marked in red $\mathrm{N}: 12269 \backslash 4712 \backslash$ Letter to Chief Draftsman.wpd


Fig. 1


Fig. 1A


Fig. 2


Fig. 3


Fig. 4


Fig. 4A


Fig. 4B


Fig. 5


Fig. 6


